

XN02401 (XN2401)

Silicon PNP epitaxial planar type

For general amplification

■ Features

- Two elements incorporated into one package
(Base-coupled transistors)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- 2SB0709A (2SB709A) × 2

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

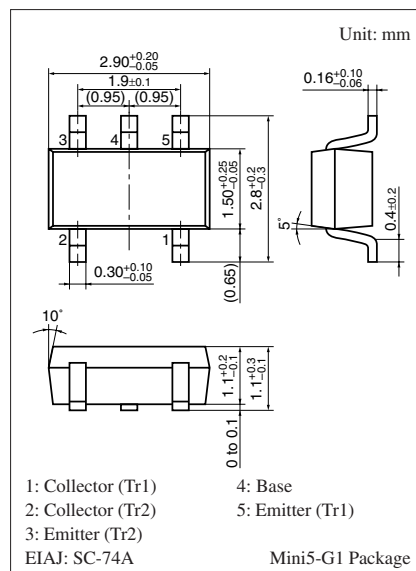
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	-60	V
Collector-emitter voltage (Base open)	V_{CEO}	-50	V
Emitter-base voltage (Collector open)	V_{EBO}	-7	V
Collector current	I_C	-100	mA
Peak collector current	I_{CP}	-200	mA
Total power dissipation	P_T	300	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = -10\ \mu\text{A}$, $I_E = 0$	-60			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = -2\ \text{mA}$, $I_B = 0$	-50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = -10\ \mu\text{A}$, $I_C = 0$	-7			V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -20\ \text{V}$, $I_E = 0$			-0.1	μA
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = -10\ \text{V}$, $I_B = 0$			-100	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = -10\ \text{V}$, $I_C = -2\ \text{mA}$	160		460	—
h_{FE} ratio *	$h_{FE(\text{Small/Large})}$	$V_{CE} = -10\ \text{V}$, $I_C = -2\ \text{mA}$	0.50	0.99		—
Collector-emitter saturation voltage	$V_{CE(\text{sat})}$	$I_C = -100\ \text{mA}$, $I_B = -10\ \text{mA}$		-0.3	-0.5	V
Transition frequency	f_T	$V_{CB} = -10\ \text{V}$, $I_E = 1\ \text{mA}$, $f = 200\ \text{MHz}$		80		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10\ \text{V}$, $I_E = 0$, $f = 1\ \text{MHz}$		2.7		pF

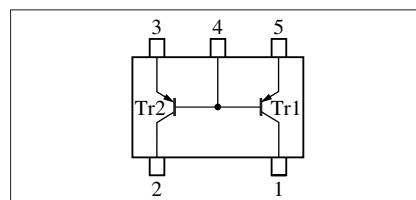
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Ratio between 2 elements

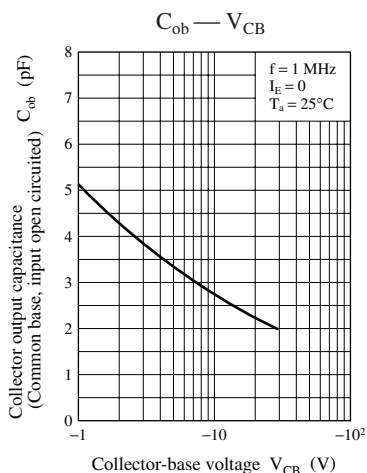
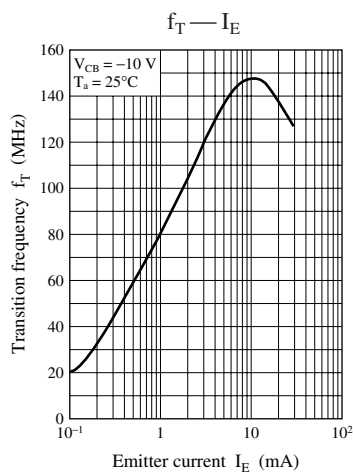
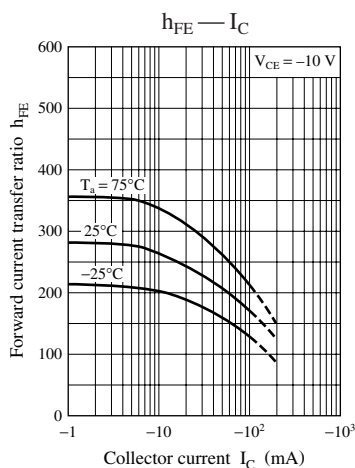
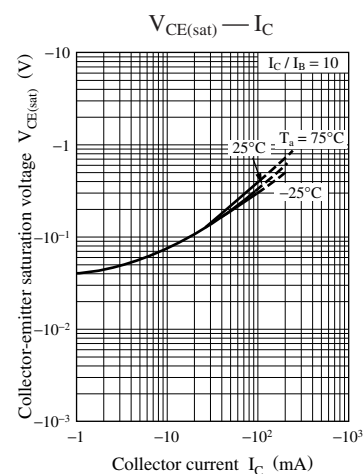
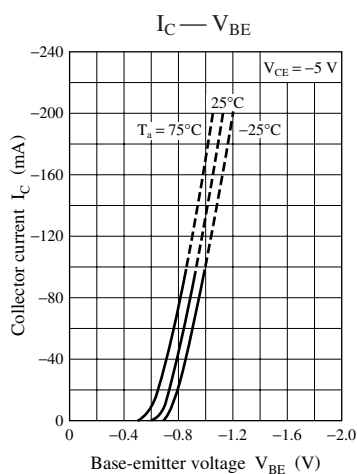
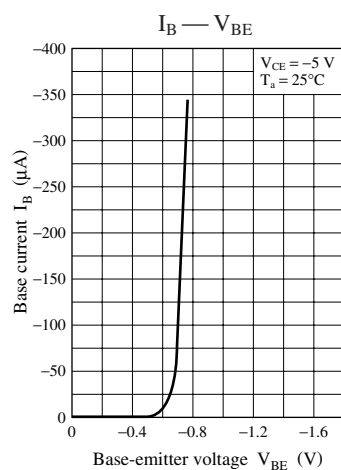
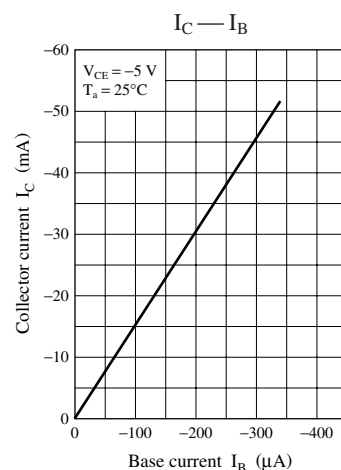
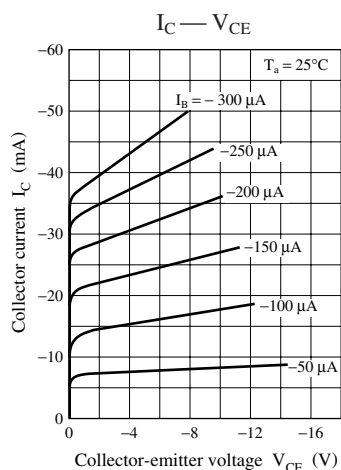
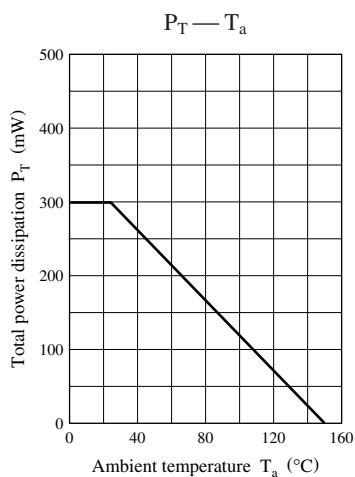


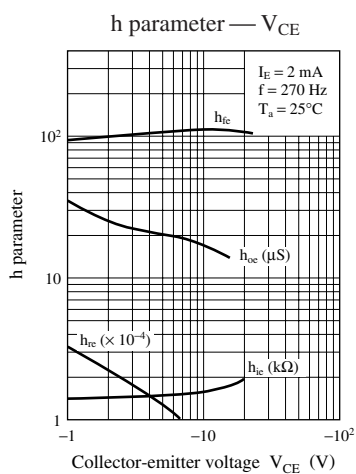
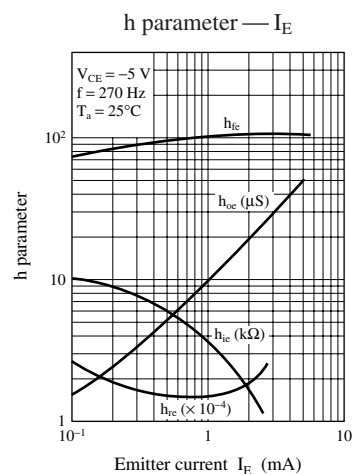
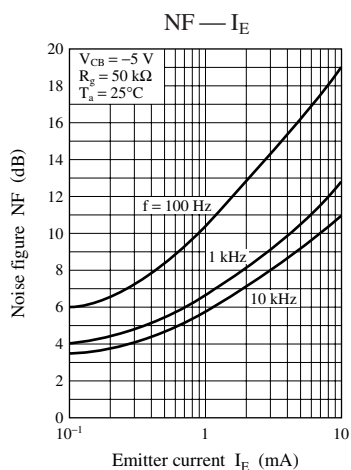
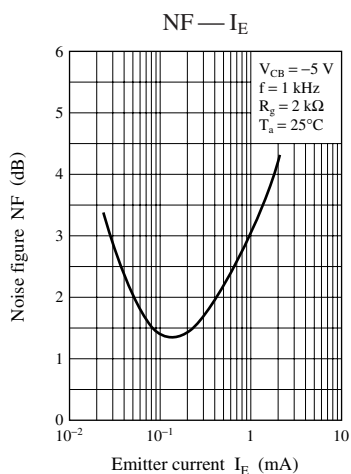
Marking Symbol: 7R

Internal Connection



Note) The part number in the parenthesis shows conventional part number.





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